orm PTO-1595 (Rev. 09/ 04)	U.S. DEPARTMENT OF CON United States Patent and Tradema	MERCE
МВ No. 0651-0027 (вир. 6/30/2005)  RECORDATION FOR		
PATENTS ONLY		
To the Director of the U.S. Patent and Trademark Office: Please record the attached documents or the new address(es) below.		
Name of conveying party(les)/Execution Date(s):	2. Name and address of receiving party(ies)	
KAZUHITO SUMIYOSHI (04/02/2008), KOJI		
MATSUURA (04/02/2008), AND HIDEKI		
ASAZU (04/02/2008)	Name: SONY CORPORATION	
	Internal Address:	
The section is a section on after inventor page	Street Address:	
Execution Date(s): in parentheses after Inventor name  Additional pame(s) of conveying party(les) attached? Yes X No	1-7-1 Konan, Minato-ku	
Additional name(s) of conveying party(les) attached? Yes X No	Tokyo	
3. Nature of Conveyance:	108-0075	
X Assignment Merger	JAPAN	
Security Agreement Change of Name	Oity:	
Government Interest Assignment	State:	
Executive Order 9424, Confirmatory License		No.
Other	attached:	
A. Patent Application No.(s) 12/011,978	B. Patent No.(s)	
Additional numbers attached	<del></del>	<del>-</del> -
<ol><li>Name and address to whom correspondence concerning document should be mailed:</li></ol>	6. Total number of applications and patents involved:	
Name: Dennis M. Smld, Esq. LERNER, DAVID, LITTENBERG, KRUMHOLZ & MENTLIK, LLP	7. Total fee (37 CFR 1.21(h) & 3.41) \$40.00	<u>o</u>
Internal Address: Atty. Dkt.:	Authorized to be charged by credit card	
Street Address: 600 South Avenue West	X Authorized to be charged to deposit account	
	Enclosed	
		rtina titla
	None required (government interest not affect	y uue
City: Westfield	8. Payment Information	
State: NJ Zip: 07090	a, Credit Card Last 4 Numbers	
Phone Number: (908) 518-6374	Expiration Date	
Fax Number: (908) 654-0415	b. Deposit Account Number 12-1095	
Email Address: dsmid@ldlkm.com	Authorized User Name Dennis M. Smid, E	sq.
9. Signature:		
1 /2:m. 10	April 25, 2008	
Signature	Date	
Dennis M. Smid, Esq 34,930	Total number of pages including cover sheet, attachments, and documents:	3
Name of Person Signing	sneet, attachments, and documents.	

871727, LDOC

PATENT REEL: 020865 FRAME: 0338 LDLKM

Docket No.: SONYJP 3.0-1553 Sony Ref. No.: S08P0105US00

## ASSIGNMENT

WHEREAS, I, as a below named inventor, residing at the address stated next to my name, am a sole inventor (if only one name is listed below) or a joint inventor (if plural names are listed below) of certain new and useful improvements in:

## INFORMATION PROCESSING APPARATUS AND METHOD, AND PROGRAM

for which application for Letters Patent of the United States of America was executed by me on the date indicated next to my name and address;

AND WHEREAS, Sony Corporation, a Japanese corporation with offices at 1-7-1 Konan, Minato-ku, Tokyo, Japan (hereinafter referenced as ASSIGNEE) is desirous of acquiring all interest in, to and under said invention, said application disclosing the invention and in, to and under any Letters Patent or similar legal protection which may be granted therefor in the United States and in any and all foreign countries;

NOW THEREFORE, in consideration of the sum of One Dollar (\$1.00), and other good and valuable consideration, the receipt and sufficiency of which are hereby acknowledged, I, as a sole or joint inventor as indicated below, by these presents do hereby assign, sell and transfer unto the said ASSIGNEE, its successors, assigns, and legal representatives, my entire right, title and interest in the said invention, said application, including any divisions and continuations thereof, and in and to any and all Letters Patent of the United States, and countries foreign thereto, which may be granted for said invention, and in and to any and all priority rights and/or convention rights under the International Convention for the Protection of Industrial Property, Inter-American Convention Relating to Patents, Designs and Industrial Models, and any other international agreements to which the United States of America adheres, and to any other benefits accruing or to accrue to me with respect to the filling of applications for patents or securing of patents in the United States and countries foreign thereto, and I hereby authorize and request the Commissioner of Patents to issue the said United States Letters Patent to said ASSIGNEE, as the assignee of the whole right, title and interest thereto;

And I further agree to execute all necessary or desirable and lawful future documents, including assignments in favor of ASSIGNEE or its designee, as ASSIGNEE or its successors, assigns and legal representatives may from time-to-time present to me and without further remuneration, in order to perfect title in said invention, modifications, and improvements in said invention, applications and Letters Patent of the United States and countries foreign thereto;

And I further agree to properly execute and deliver and without further remuneration, such necessary or desirable and lawful papers for application for foreign patents, for filing subdivisions of said application for patent, and or, for obtaining any reissue or reissues of any Letters Patent which may be granted for my aforesaid invention, as the ASSIGNEE thereof shall hereafter require and prepare at its own expense;

And I further agree that ASSIGNEE will, upon its request, be provided promptly with all pertinent facts and documents relating to said application, said invention and said Letters Patent and legal equivalents in foreign countries as may be known and accessible to me and will testify as to the same in any interference or litigation related thereto;

And I hereby covenant that no assignment, sale, agreement or encumbrance has been or will be made or entered into which would conflict with this assignment and sale.

And I hereby authorize and request my attorney(s) of record in this application to insert the application number and filing date of this application in the spaces that follow: Application Number: 12/011.978; Filing Date: January 30, 2008.

This assignment executed on the dates indicated below.

<u>Kazuhito Sumiyoshi</u>		
Name of First or Solc Inventor	Execution Date of U.S. Patent Application	
<u>Tokyo, Japan</u>		
Residence of First or Sole Inventor		
Signature of First or Sole Inventor	april 2. 2008	
Signature of First or Sole Inventor	Date of this Assignment	

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PATENT REEL: 020865 FRAME: 0339 \_ . \_ \_

Docket No.: SONYJP 3.0-1553 Sony Ref. No.: S08P0105US00

Page 2

Koji Matsuura	
Name of Second Joint Inventor	Execution Date of U.S. Patent Application
Tokvo, Japan	
Residence of Second Joint Inventor	
Joy: Matsuura	april 2, 2008
Signature of Second Joint Inventor	Date of this Assignment
<u>Hideki</u> Asazu	<u> </u>
Name of Third Joint Inventor	Execution Date of U.S. Patent Application
Tokyo, Japan	
Residence of Third Joint Inventor	
Signature of Third Joint Inventor	April 2, 2008
Signature of Third Joint Inventor	Date of this Assignment

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PATENT REEL: 020865 FRAME: 0340

**RECORDED: 04/25/2008**